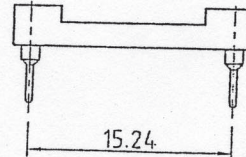
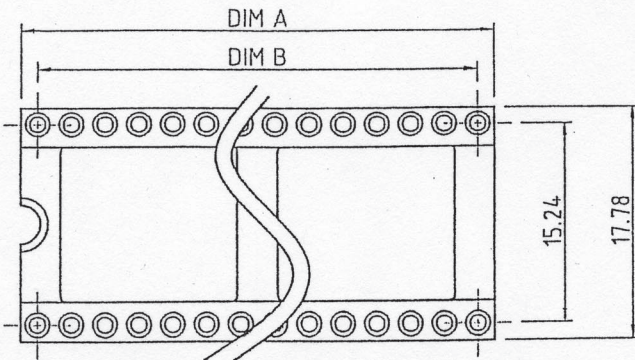


1 2 3 4 5 6 7

A

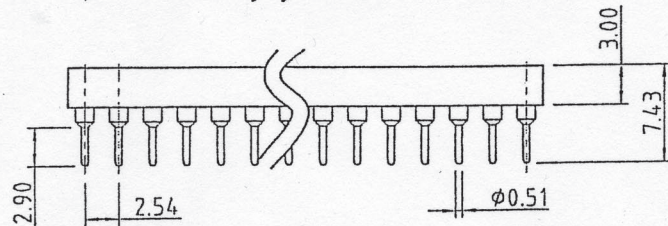


B

A

B

C



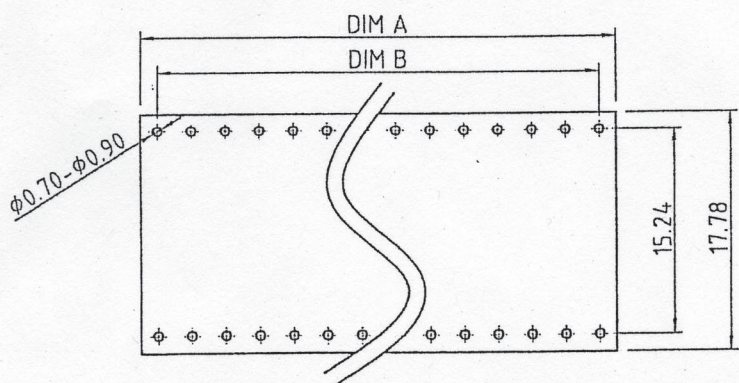
C

D

P.C.B. LAYOUT

D

E



E

Contact	DIM A	DIM B
24	30.48	27.94
28	35.56	33.02
32	40.64	38.10
40	50.80	48.26

F

F

- Pin: brass. machined, CuZn38Pb2
- Clip: contact 4 finger: Beryllium copper, heat treated
- plating: HZL = Pin - 200µ" / Clip - gold flash  
HGL = Pin - gold flash / Clip - gold flash
- Insulator body: polyamide ( glass filled ) , UL94V-0
- Current rating: 3A / contact max.
- Contact resistance: <4mOhm / contact
- Insulations resistance: >1000Mohm at V=100V
- Operating: 60 vac / dc
- Operating temperature: gold plated: -55°C to +125°C  
tin plated: -40°C to +105°C
- Soldering temperature: +260°C, 10s max.
- Mechanical life: min.200

G

G

H

H

I

I

K

K

Änderung	Datum	Name	Datum	Name
			Bearb. 07.11.01	Hellwig
			Gepr. 07.11.01	<i>Hellwig</i>
			Norm.	

Benennung  
**IC-sockets  
 with machined pins  
 AR xx - HZL-TT  
 AR xx - HGL-TT**

Zeichnungsnummer  
**ASS 1186B CO**

Blatt  
**1/1**

Ersatz für ASS 0337 CO  
 dd. 19.06.2001

Blatt

**ASSMANN**  
 Electronic Components

1 2 3 4 5 6 7